



P-Channel 20-V (D-S) MOSFET

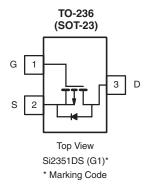
MOSFET PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)		
- 20	$0.115 \text{ at V}_{GS} = -4.5 \text{ V}$	- 3.0	3.2 nC		
	0.205 at V _{GS} = - 2.5 V	- 2.2	3.2110		

FEATURES

- Halogen-free Option Available
- TrenchFET[®] Power MOSFET
- PWM Optimized
- 100 % R_g Tested



ROHS COMPLIANT



Ordering Information: Si2351DS-T1-E3 (Lead (Pb)-free) Si2351DS-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS $T_A = 2$	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	- 20			
Gate-Source Voltage	V_{GS}	± 12	V		
	T _C = 25 °C		- 2.8		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	I _D	- 2.4		
Continuous Diain Guitent (1) = 130 G)	T _A = 25 °C	'D	- 2.2 ^{b, c}		
	T _A = 70 °C		- 1.8 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	- 10		
0 11 0 0 0 1	T _C = 25 °C		- 2.0		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 0.91 ^{b, c}		
	T _C = 25 °C		2.1		
Maximum Power Dissipation	T _C = 70 °C	P _D	1.5	w	
Maximum Fower Dissipation	T _A = 25 °C	ט י	1.0 ^{b, c}		
	T _A = 70 °C		0.7 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, d}	≤ 5 s	R _{thJA}	90	115	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	60	75] 0/11	

Notes:

- a. Based on T_C = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under Steady State conditions is 130 °C/W.

Si2351DS

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	·			•	<u>'</u>		
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 vA		- 16.7		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- I _D = - 250 μA		2.1			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.6		- 1.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V			- 1		
		V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C			- 10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 10			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 2.4 A		0.092	0.115		
		V _{GS} = - 2.5 V, I _D = - 1.8 A		0.164	0.205	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 2.4 A		5.5		S	
Dynamic ^b		,		1		l	
Input Capacitance	C _{iss}			250		pF	
Output Capacitance	C _{oss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		80			
Reverse Transfer Capacitance	C _{rss}			55			
Total Cata Charge	Q_g	$V_{DS} = -10 \text{ V}, V_{GS} = -5.0 \text{ V}, I_{D} = -2.4 \text{ A}$		3.4	5.1	nC	
Total Gate Charge				3.2	5		
Gate-Source Charge	Q_{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -2.4 \text{ A}$		0.5			
Gate-Drain Charge	Q_{gd}			1.4			
Gate Resistance	R_g	f = 1 MHz		8.5	13	Ω	
Turn-On Delay Time	t _{d(on)}			9	14		
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_L = 5.26 \Omega$		30	45	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 1.9 A, V_{GEN} = - 4.5 V, R_G = 1 Ω		32	48		
Fall Time	t _f			16	24		
Drain-Source Body Diode Characteristic	s			•		•	
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 2.0	А	
Pulse Diode Forward Current ^a	I _{SM}				- 10		
Body Diode Voltage	V _{SD}	I _S = - 2.0 A		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			17	26	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 0 0 4 di/dt 100 4/:- T 05 00		5	8	nC	
Reverse Recovery Fall Time	t _a	$I_F = -2.0 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s, T}_J = 25 ^{\circ}\text{C}$		14			
Reverse Recovery Rise Time	t _b			3		ns	

Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

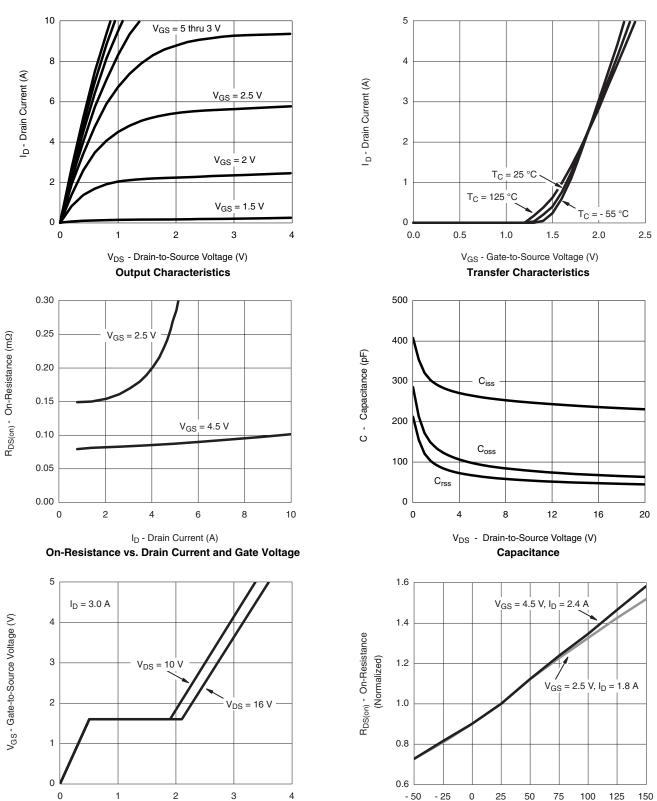
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.







TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Q_q - Total Gate Charge (nC)

Gate Charge

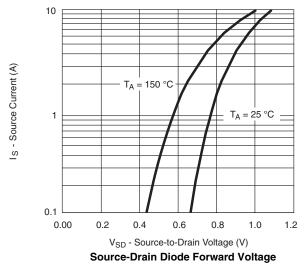
T_J - Junction Temperature (°C)

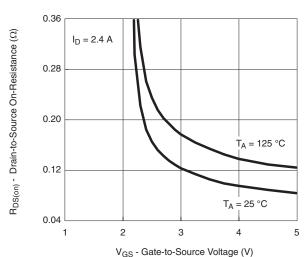
On-Resistance vs. Junction Temperature

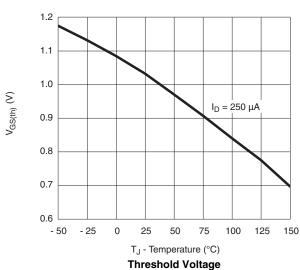
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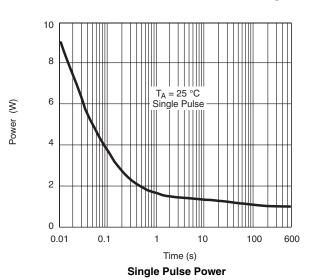
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

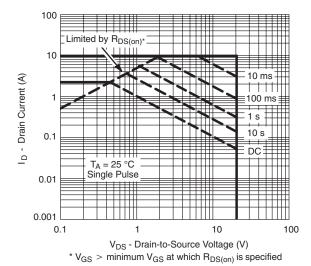






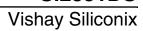
On-Resistance vs. Gate-to-Source Voltage





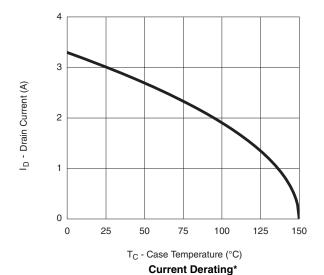
Safe Operating Area

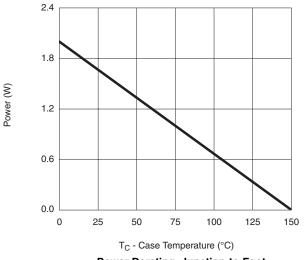






TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





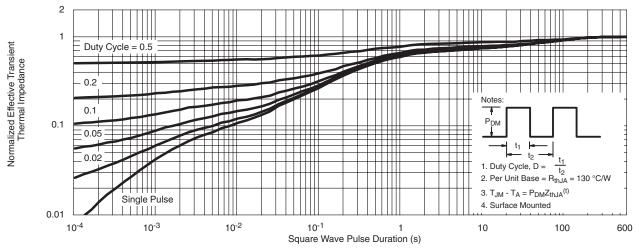
Power Derating, Junction-to-Foot

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

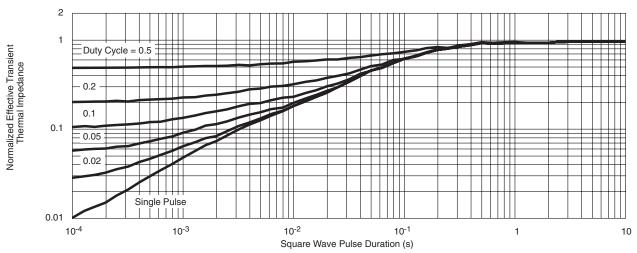
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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